

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-7 (canceled).

Claim 8 (new): A laminated ceramic electronic component comprising:

a plurality of ceramic sheets, each including an internal conductor pattern having a first land at one end of the internal conductor pattern and a second land at the other end and having a via hole provided therein, the plurality of ceramic sheets being laminated to define a laminate; wherein

the via hole is filled with a conductive material;

the internal conductor patterns disposed on different ones of the plurality of ceramic sheets are electrically connected to each other through the via hole;

the first land is arranged so as to cover the via hole and the first land provided in one of the plurality of ceramic sheets is electrically connected to the second land provided in another of the plurality of ceramic sheets through the via hole provided in the one ceramic sheet; and

the second land is larger than the first land.

Claim 9 (new): The laminated ceramic electronic component according to Claim 8, wherein the second land extends from a projection plane of the first land to a projection plane of the coil conductor pattern.

Claim 10 (new): The laminated ceramic electronic component according to Claim 8, wherein the area of the second land is about 1.10 to about 2.25 times as wide as the area of the first land.

Claim 11 (new): The laminated ceramic electronic component according to Claim 8, wherein the internal conductors included on the plurality of ceramic sheets define a spiral coil.

Claim 12 (new): The laminated ceramic electronic component according to Claim 11, wherein terminal ends of the spiral coil define lead-out electrodes.

Claim 13 (new): The laminated ceramic electronic component according to Claim 11, further comprising two additional ceramic sheets which do not include any internal conductors disposed therein, one of the two additional ceramic sheets being disposed on an upper surface of the laminate, and the other of the two additional ceramic sheets being disposed on a lower surface of the laminate.

Claim 14 (new): A manufacturing method for a laminated ceramic electronic component, comprising the steps of:

printing an internal conductor pattern having a first land at one end of the internal conductor pattern and a second land at the other end on the surface of a ceramic sheet having a hole for a via hole formed therein by using a conductive material such that the first land covers the hole for via hole;

filling the conductive material in the hole for the via hole; and

laminating a plurality of ceramic sheets such that the first land in one of the plurality of ceramic sheets is electrically connected to the second land in another of the plurality of ceramic sheets through the via hole formed in the one of the plurality of ceramic sheets to obtain a laminate; wherein

the second land is larger than the first land.

Claim 15 (new): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein the second land extends from a projection plane of the first land to a projection plane of the coil conductor pattern.

Claim 16 (new): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein the area of the second land is about 1.10 to about 2.25 times as wide as the area of the first land.

Claim 17 (new): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein the internal conductor pattern is printed on a ceramic sheet having the hole for the via hole formed therein and the hole for the via hole is filled with a conductive material, without providing a carrier film on a back surface of the ceramic sheet.

Claim 18 (new): The manufacturing method for a laminated ceramic electronic component according to Claim 14, further comprising the step of:

arranging the internal conductors on the plurality of ceramic sheets so as to define a spiral coil.

Claim 19 (new): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein terminal ends of the spiral coil define lead-out electrodes.

Claim 20 (new): The manufacturing method for a laminated ceramic electronic component according to Claim 14, further comprising the steps of:

providing two additional ceramic sheets which do not include any internal conductors printed therein;

disposing one of the two additional ceramic sheets on an upper surface of the laminate; and

disposing the other of the two additional ceramic sheets on a lower surface of the laminate.

## REMARKS

Claims 8-20 are pending in this application. By this Preliminary Amendment, Applicants AMEND the specification, the title of the invention, the abstract of the disclosure, and the drawings, CANCEL claims 1-7 and ADD new claims 8-20.

Applicants have attached hereto a Substitute Specification in order to make corrections of minor informalities contained in the originally filed specification. Applicants' undersigned representative hereby declares and states that the Substitute Specification filed concurrently herewith does not add any new matter whatsoever to the above-identified patent application. Accordingly, entry and consideration of the Substitute Specification are respectfully requested.

The changes to the specification have been made to correct minor informalities to facilitate examination of the present application.

Applicants respectfully submit that this application is in condition for allowance. Favorable consideration and prompt allowance are respectfully solicited.

Respectfully submitted,

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